



STP10NK80ZFP STP10NK80Z - STW10NK80Z

N-CHANNEL 800V - 0.78Ω - 9A - TO-220/FP-TO-247
Zener-Protected SuperMESH™ MOSFET

General features

Type	V _{DSS}	R _{DS(on)}	I _D	P _w
STW10NK80Z	800 V	<0.90 Ω	9 A	160 W
STP10NK80Z	800 V	<0.90 Ω	9 A	160 W
STP10NK80ZFP	800 V	<0.90 Ω	9 A	40 W

- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- GATE CHARGE MINIMIZED
- VERY LOW INTRINSIC CAPACITANCES
- VERY GOOD MANUFACTURING REPEATABILITY

Description

The SuperMESH™ series is obtained through an extreme optimization of ST's well established strip-based PowerMESH™ layout. In addition to pushing on-resistance significantly down, special care is taken to ensure a very good dv/dt capability for the most demanding applications.

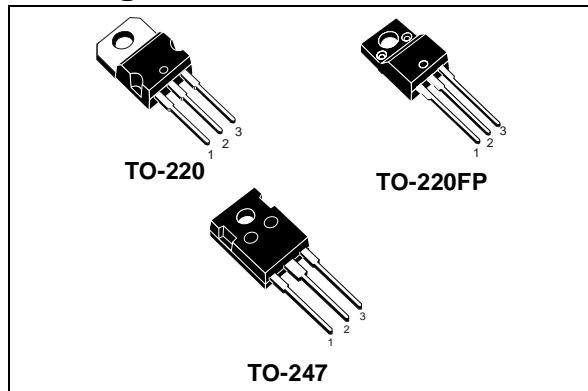
Applications

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES
- DC-AC CONVERTERS FOR WELDING, UPS AND MOTOR DRIVE

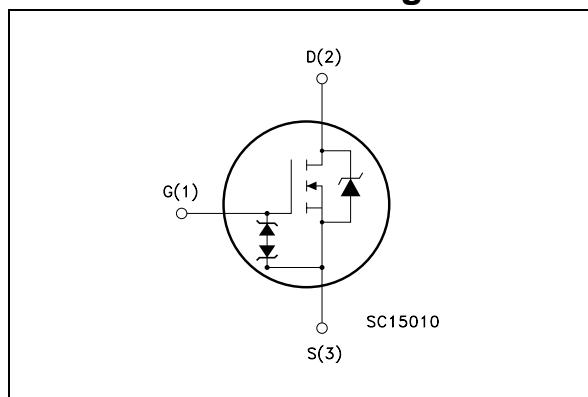
Order codes

Sales Type	Marking	Package	Packaging
STP10NK80Z	P10NK80Z	TO-220	TUBE
STP10NK80ZFP	P10NK80ZFP	TO-220FP	TUBE
STW10NK80Z	W10NK80Z	TO-247	TUBE

Package



Internal schematic diagram



1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220/ TO-247	TO-220FP	
V_{DS}	Drain-Source Voltage ($V_{GS} = 0$)	800		V
V_{DGR}	Drain-gate Voltage ($R_{GS} = 20\text{k}\Omega$)	800		V
V_{GS}	Gate-Source Voltage	± 30		V
I_D	Drain Current (continuous) at $T_C = 25^\circ\text{C}$	9	9 (<i>Note 1</i>)	A
I_D	Drain Current (continuous) at $T_C = 100^\circ\text{C}$	6	6 (<i>Note 1</i>)	A
I_{DM} <i>Note 2</i>	Drain Current (pulsed)	36	36 (<i>Note 1</i>)	A
P_{TOT}	Total Dissipation at $T_C = 25^\circ\text{C}$	160	40	W
	Derating Factor	1.28	0.32	$\text{W}/^\circ\text{C}$
$V_{esd(G-S)}$	G-S ESD (HBM C=100pF, R=1.5k Ω)	4		KV
dv/dt <i>Note 3</i>	Peak Diode Recovery voltage slope	4.5		V/ns
V_{ISO}	Insulation Withstand Volatge (DC)	--	2500	V
T_j T_{stg}	Operating Junction Temperature Storage Temperature	-55 to 150		$^\circ\text{C}$

Table 2. Thermal data

		TO-220	TO-220FP	TO-247	Unit
$R_{thj-case}$	Thermal Resistance Junction-case Max	0.78	3.1	0.78	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal Resistance Junction-amb Max	62.5		50	$^\circ\text{C}/\text{W}$
T_I	Maximum Lead Temperature For Soldering Purpose	300			$^\circ\text{C}$

Table 3. Avalanche characteristics

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, repetitive or Not-Repetitive (pulse width limited by T_j max)	9	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_j=25^\circ\text{C}$, $I_D=I_{AR}$, $V_{DD}=50\text{V}$)	290	mJ

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	800			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}, V_{DS} = \text{Max Rating}, T_c = 125^\circ\text{C}$			1 50	μA μA
I_{GSS}	Gate Body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 100 \mu\text{A}$	3	3.75	4.5	V
$R_{DS(\text{on})}$	Static Drain-Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}$		0.78	0.9	Ω

Table 5. Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_f <i>Note 4</i>	Forward Transconductance	$V_{DS} = 15 \text{ V}, I_D = 4.5 \text{ A}$		9.6		S
C_{iss} C_{oss} C_{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$		2180 205 38		pF pF pF
$C_{oss \text{ eq.}}$ <i>Note 5</i>	Equivalent Output Capacitance	$V_{GS} = 0, V_{DS} = 0 \text{ V} \text{ to } 640 \text{ V}$		105		pF
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 640 \text{ V}, I_D = 9 \text{ A}$ $V_{GS} = 10 \text{ V}$ (see Figure 19)		72 12.5 37	101	nC nC nC

Table 6. Switching times

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 400 \text{ V}, I_D = 4.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 20)		30 20		ns ns
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time	$V_{DD} = 400 \text{ V}, I_D = 4.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 20)		65 17		ns ns
$t_{r(Voff)}$ t_f t_c	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 640 \text{ V}, I_D = 9 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 20)		13 10 25		ns ns ns

Table 7. Gate-source zener diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{GSO} <i>Note 6</i>	Gate-Source Breakdown Voltage	$I_{GS}=\pm 1\text{mA}$ (Open Drain)	30			V

Table 8. Source drain diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM} <i>Note 2</i>	Source-drain Current Source-drain Current (pulsed)				9 36	A A
V_{SD} <i>Note 4</i>	Forward on Voltage	$I_{SD}=9\text{ A}, V_{GS}=0$			1.6	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD}=9\text{A}, di/dt = 100\text{A}/\mu\text{s},$ $V_{DD}=45\text{ V}, T_j=150^\circ\text{C}$		645 6.4 20		ns μC A

(1)Limited only by maximum temperature allowed

(2) Pulse width limited by safe operating area

(3) $I_{SD} \leq 9\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_j \leq T_{JMAX}$ (4) Pulsed: pulse duration = 300 μs , duty cycle 1.5%(5) $C_{oss eq}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80%

(6) The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

2.1 Electrical characteristics (curves)

Figure 1. Safe Operating Area for TO-220

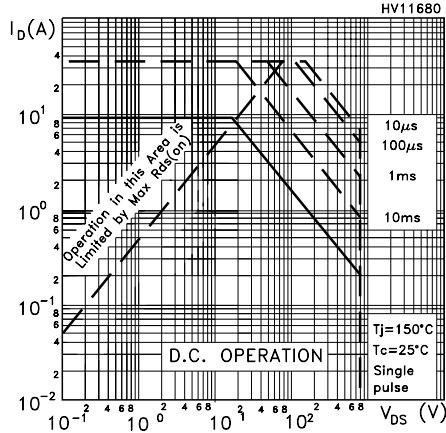


Figure 3. Safe Operating Area for TO-220FP

Figure 2. Thermal Impedance for TO-220

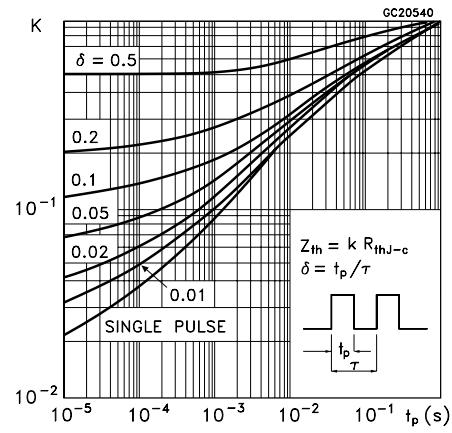


Figure 4. Thermal Impedance for TO-220FP

D.C. OPERATION

$T_j = 150^\circ\text{C}$

$T_c = 25^\circ\text{C}$

Single pulse

Operation is limited by MOS rate.

Figure 5. Safe Operating Area for TO-247

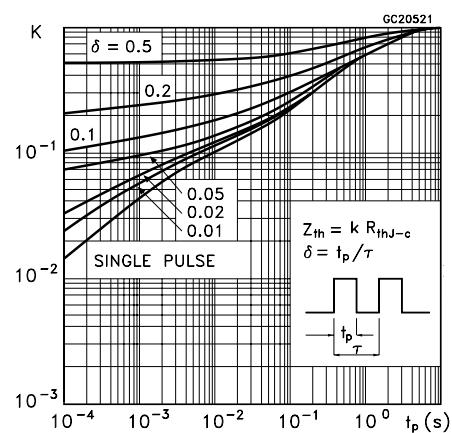


Figure 6. Thermal Impedance for TO-247

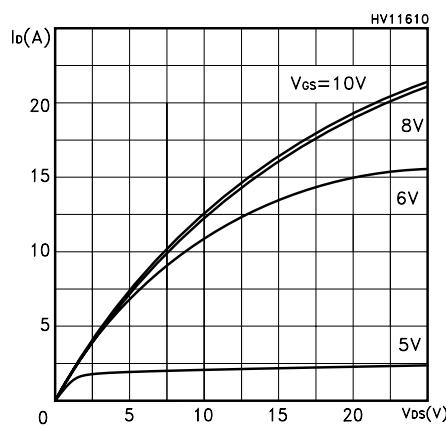
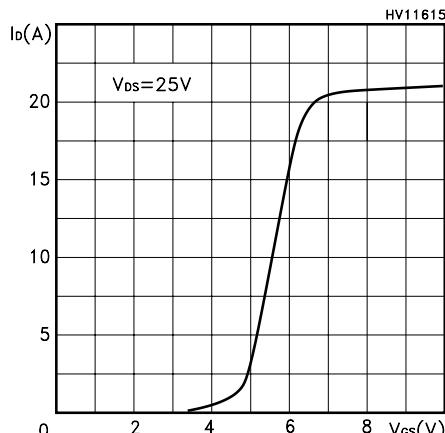
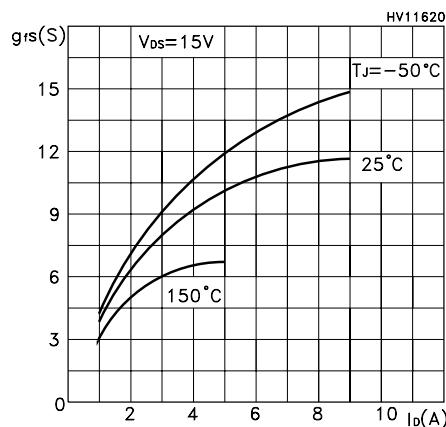
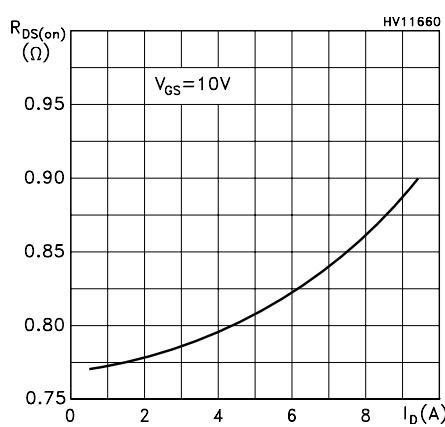
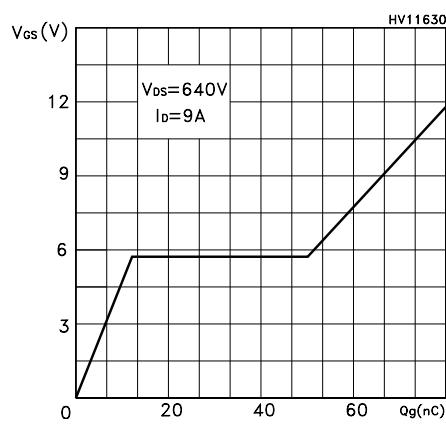
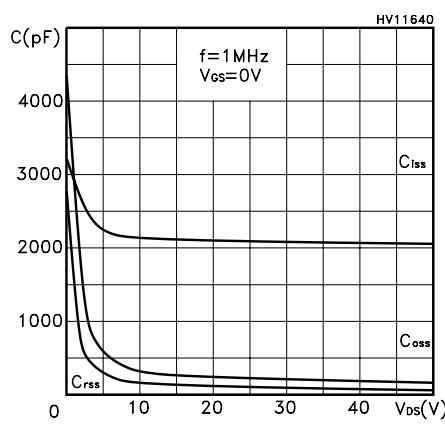
Figure 7. Output Characteristics**Figure 8. Transfer Characteristics****Figure 9. Transconductance****Figure 10. Static Drain-Source on Resistance****Figure 11. Gate Charge vs Gate-Source Voltage****Figure 12. Capacitance Variations**

Figure 13. Normalized Gate Threshold Voltage vs Temperature

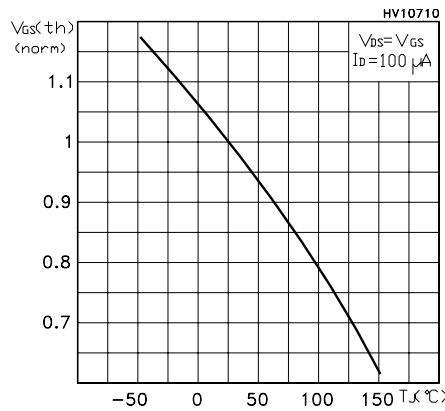


Figure 15. Source-drain Diode Forward Characteristics

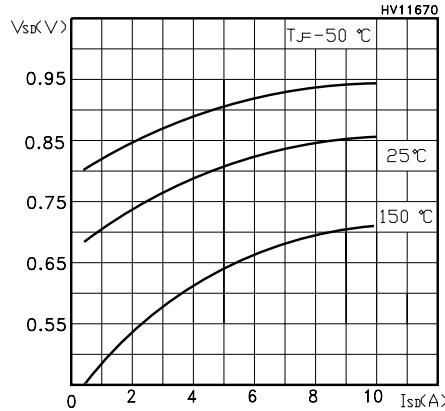


Figure 17. Maximum Avalanche Energy vs Temperature

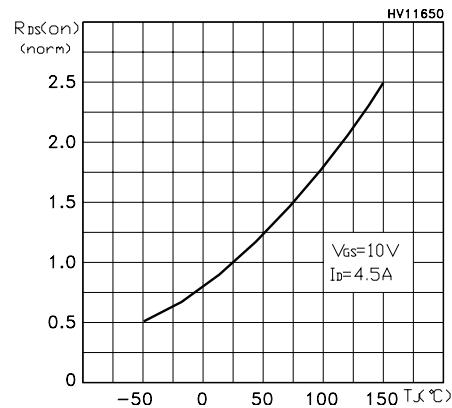
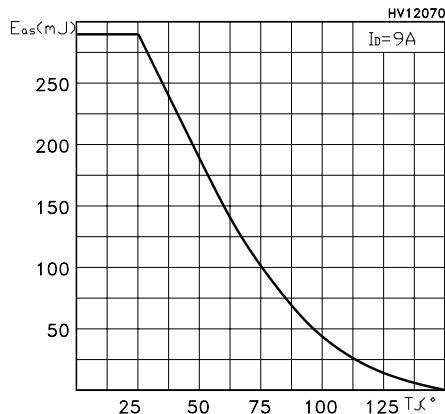
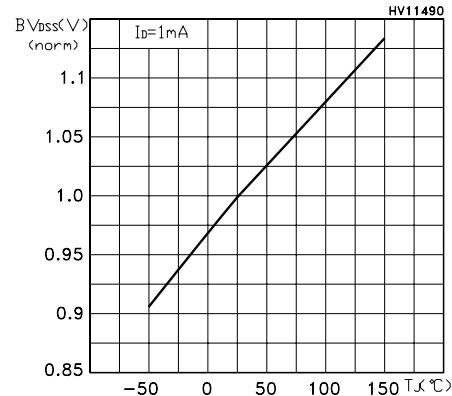


Figure 16. Normalized BVDSS vs Temperature



3 Test circuits

Figure 18. Switching Times Test Circuit For Resistive Load

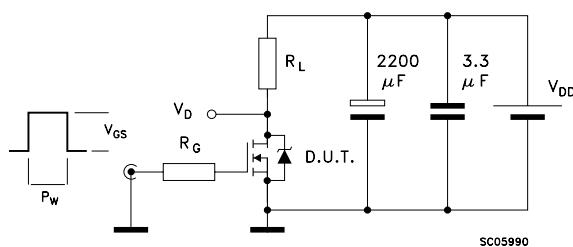


Figure 19. Gate Charge Test Circuit

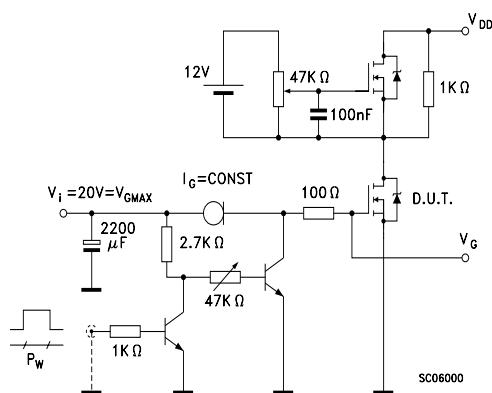
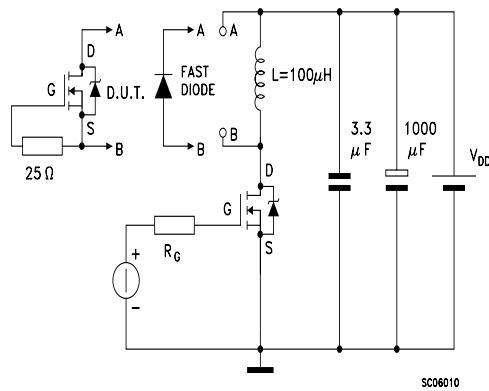


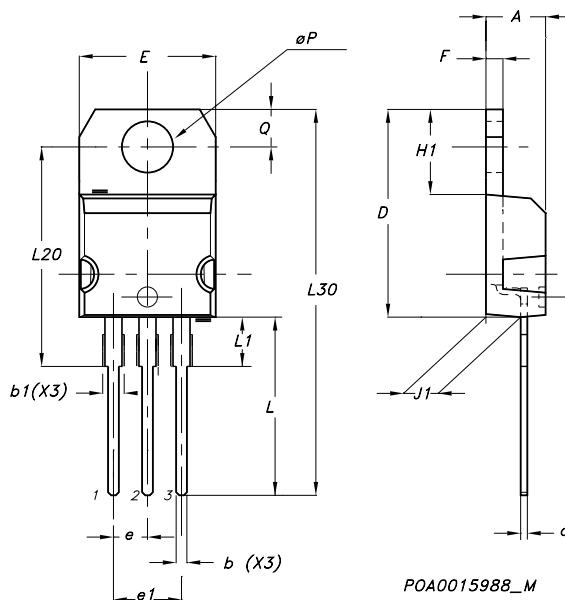
Figure 20. Test Circuit For Inductive Load Switching and Diode Recovery Times



4 Package mechanical data

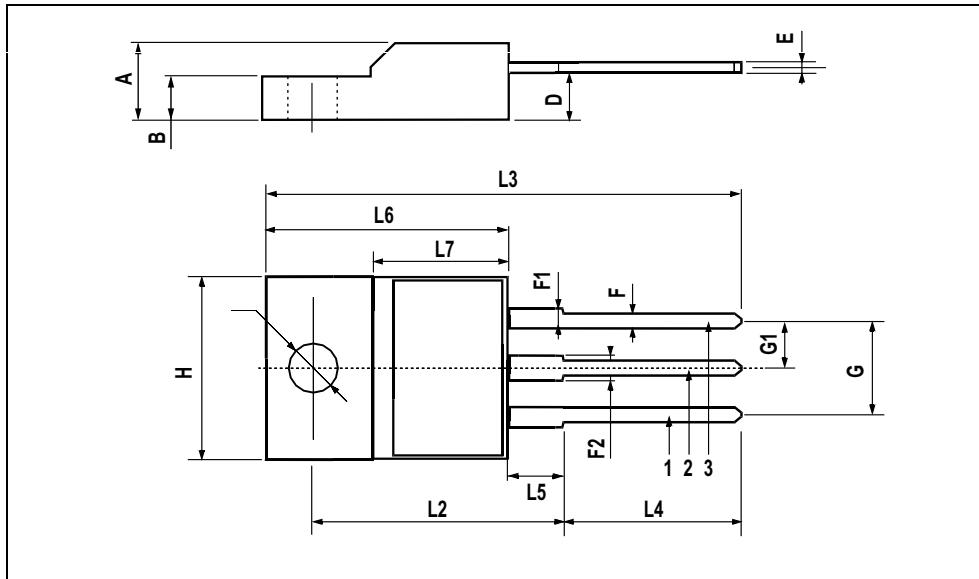
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-220 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
ϕP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



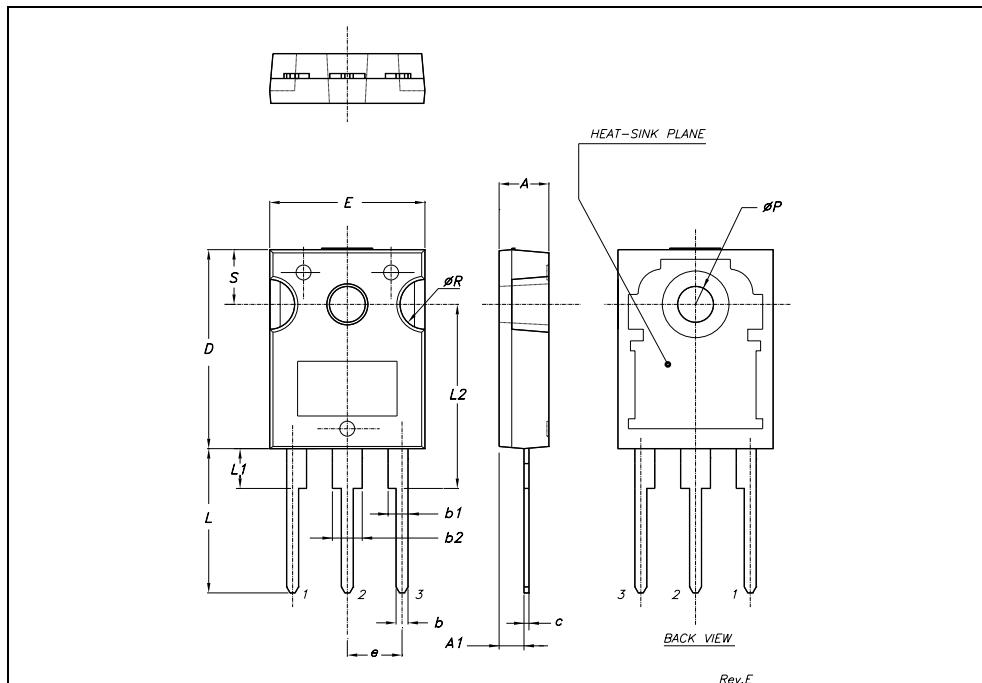
TO-220FP MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2	16			0.630		
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
\emptyset	3		3.2	0.118		0.126

DIM.	mm.			inch		
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2	16			0.630		
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
\emptyset	3		3.2	0.118		0.126



TO-247 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.85		5.15	0.19		0.20
A1	2.20		2.60	0.086		0.102
b	1.0		1.40	0.039		0.055
b1	2.0		2.40	0.079		0.094
b2	3.0		3.40	0.118		0.134
c	0.40		0.80	0.015		0.03
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
e		5.45			0.214	
L	14.20		14.80	0.560		0.582
L1	3.70		4.30	0.14		0.17
L2		18.50			0.728	
ϕP	3.55		3.65	0.140		0.143
ϕR	4.50		5.50	0.177		0.216
S		5.50			0.216	



5 Revision History

Date	Revision	Changes
30-Aug-2005	2	Inserted new package (D ² PAK)

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